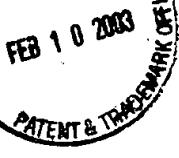


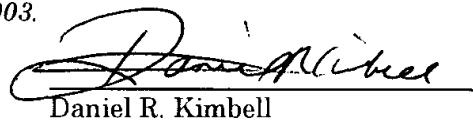
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
AMENDMENT TRANSMITTAL LETTER



I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to Commissioner of Patents and Trademarks, Washington, D.C. 20231 on February 3, 2003.

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Daniel R. Kimbell

Applicant : Rong-Fuh Shyu
Application No. : 09/383,150
Filed : August 25, 1999
Title : LEAD FRAME FOR A SEMICONDUCTOR CHIP PACKAGE, SEMICONDUCTOR CHIP PACKAGE INCORPORATING MULTIPLE INTEGRATED CIRCUIT CHIPS, AND METHOD OF FABRICATING A SEMICONDUCTOR CHIP...
Grp./Div. : 2826
Examiner : Fetsum Abraham
Docket No. : 35761/DBP/S295

Assistant Commissioner for Patents
Washington, D.C. 20231

Post Office Box 7068
Pasadena, CA 91109-7068
February 3, 2003

Enclosed is an amendment to the above-identified application.

CLAIMS AS AMENDED						
	Claims Remaining After Amendment	Highest Number Paid For	Number Extra Claims	Small Entity Rate	Large Entity Rate	FEE
Total Claims Fee	4	* 20		x \$9.00	x \$18.00	
Independent Claims	1	** 3		x \$42.00	x \$84.00	
Multiple Dependent Claims ***				\$140.00	\$280.00	
TOTAL FILING FEE						\$
NO ADDITIONAL FEE REQUIRED ****	IF NO FEE REQUIRED, INSERT "0"					0
LIST INDEPENDENT CLAIMS: 1						
* IF HIGHEST NUMBER PREVIOUSLY PAID FOR IS 20 OR LESS, WRITE "20" IN COLUMN 3						
** IF HIGHEST NUMBER PREVIOUSLY PAID FOR IS 3 OR LESS, WRITE "3" IN COLUMN 3						
*** PAY THIS FEE ONLY WHEN MULTIPLE DEPENDENT CLAIMS ARE ADDED FOR THE FIRST TIME						
**** IF NO FEE REQUIRED, ADDRESS ENVELOPE TO "BOX NON-FEE AMENDMENTS"						

Attached is our check for \$ to pay the fees calculated above.

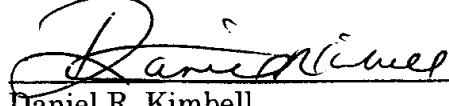
Amendment Transmittal Letter
Application No. 09/383,150

- Attached is our check for \$ to pay the fees calculated above.
 A Petition for Extension of Time and the required fee are enclosed.
 Other enclosures: Return Postcard

The Commissioner is hereby authorized to charge any fees under 37 CFR 1.16 and 1.17 which may be required by or to give effect to this paper to Deposit Account No. 03-1728. Please show our docket number with any charge or credit to our Deposit Account.

Respectfully submitted,

CHRISTIE, PARKER & HALE, LLP

By 
Daniel R. Kimbell
Reg. No. 34,849
626/795-9900

DRK/eaj
EAJ PAS486807.1--2/3/03 4:02 PM

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



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AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Post Office Box 7068
Pasadena, CA 91109-7068
February 3, 2003

Commissioner:

In response to the Office action of September 3, 2002, please amend the above-identified application as follows:

In the Claims:

Please cancel claims 1-8, and add new claims 9-12 as follows.

9. A semiconductor chip package, comprising:

a lead frame including a frame body, at least two chip-receiving windows formed in said frame body, a plurality of internal connection